SCDS031I - MAY 1996 - REVISED OCTOBER 2000

PACKAGE

- Members of Texas Instruments' Widebus™ Family
- Standard '16244-Type Pinout
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels

description

The 'CBT16244 devices provide 16 bits of high-speed TTL-compatible bus switching in a standard '16244 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

These devices are organized as four 4-bit low-impedance switches with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the switch is on, and data can flow from port A to port B, or vice versa. When \overline{OE} is high, the switch is open, and the high-impedance state exists between the two ports.

SN74CBT16244		,	
	,	,	
2B3 2B4 3B1 3B2 GND 3B3 3B4 V _{CC} 4B1 4B2 GND 4B3 4B4 4OE	12 13 14 15 16 17 18 19 20 21 22 23 24	37 2A4 36 3A1 35 3A2 34 GND 33 3A3 32 3A4 31 V _{CC} 30 4A1 29 4A2 28 GND 27 4A3 26 4A4 25 3OE	

ORDERING INFORMATION

TA	PACKA	GEŤ	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
1000 1- 0500	SSOP – DL	Tube	SN74CBT16244DL	CBT16244		
	330F - DL	Tape and reel	SN74CBT16244DLR	CB110244		
–40°C to 85°C	TSSOP – DGG	Tape and reel	SN74CBT16244DGGR	CBT16244		
	TVSOP – DGV	Tape and reel	SN74CBT16244DGVR	CY244		
–55°C to 125°C	CFP – WD	Tube	SNJ54CBT16244WD	SNJ54CBT16244WD		

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUN	ICTIC	DN T	ABLE
(each	4-bit	bus	switch)

INPUT OE	OUTPUTS A, B
L	A port = B port
н	Disconnect



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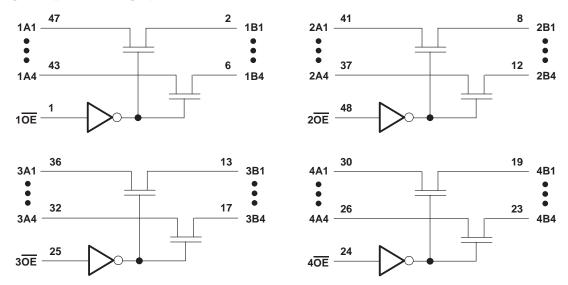
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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input voltage range, V _I (see Note 1)		–0.5 V to 7 V
Continuous channel current		128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)		–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	DGG package	70°C/W
	DGV package	58°C/W
	DL package	63°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed. 2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		SN54CB	T16244	SN74CB	T16244	UNIT
		MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	4	5.5	4	5.5	V
VIH	High-level control input voltage	2		2		V
VIL	Low-level control input voltage		0.8		0.8	V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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	METER	TEAT OOL			SN5	4CBT16	244	SN7	4CBT16	244	
PARA	METER	TEST CON	IDITIONS		MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT
VIK		V _{CC} = 4.5 V,	lj = -18 mA				-1.2			-1.2	V
1.		VCC = 0	VI = 5.5 V				10			10	A
łı		V _{CC} = 5.5 V	V _I = 5.5 V or GND				±1			±1	μA
ICC		$V_{CC} = 5.5 V,$ $V_{I} = V_{CC} \text{ or GND}$	IO = 0,				3.2	i		3	μA
ΔI_{CC}^{\ddagger}	Control inputs	$V_{CC} = 5.5 V$, Other inputs at V_{CC} or GND	One input at	3.4 V,			2.5			2.5	mA
Ci	Control inputs	$V_{I} = 3 V \text{ or } 0$				2.5			2.5		pF
Cio(OFI	 F)	V _O = 3 V or 0,	$\overline{OE} = V_{CC}$			4.5			4.5		рF
		$V_{CC} = 4 V,$	V _I = 2.4 V,	l _l = 15 mA			20			20	
r _{on} §			$V_{I} = 0,$	l _l = 64 mA		5	10		5	7	
rons		$V_{CC} = 4.5 V$	$V_{ } = 0,$	l _l = 30 mA		5	10		5	7	Ω
			V _I = 2.4 V,	lj = 15 mA		8	14		8	12	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. [‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

§ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

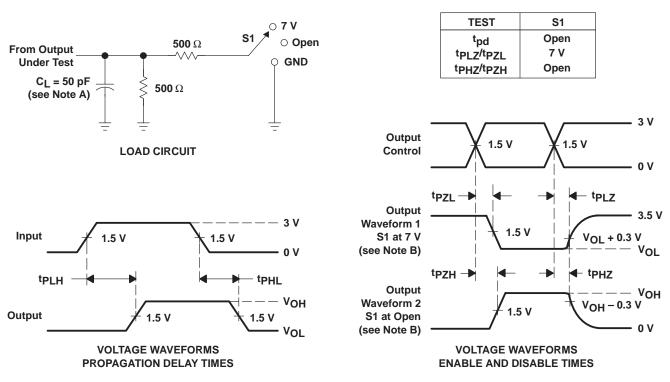
Γ					SN54CB	T16244			SN74CE	BT16244		
	PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} :	= 4 V	۲ <mark>۰۵</mark> کا ۲۰۱۰ ±	= 5 V 5 V	V _{CC} :	= 4 V	۲ <mark>۰۵</mark> × V _{CC}	= 5 V 5 V	UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
Γ	t _{pd} ¶	A or B	B or A				0.8*		0.35		0.25	ns
Γ	ten	OE	A or B		10.3	1	9.2		5.5	1	5.1	ns
	^t dis	OE	A or B		9.7	1	8.2		5.2	1	5.4	ns

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



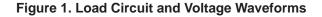
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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
 Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .





PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9855301QXA	ACTIVE	CFP	WD	48	1	TBD	A42 SNPB	N / A for Pkg Type
74CBT16244DGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74CBT16244DGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74CBT16244DGVRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74CBT16244DGVRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16244DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16244DGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16244DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16244DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16244DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16244DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54CBT16244WD	ACTIVE	CFP	WD	48	1	TBD	A42 SNPB	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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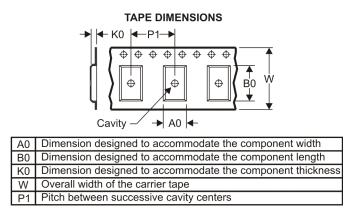
PACKAGE OPTION ADDENDUM

18-Sep-2008

to Customer on an annual basis.

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal	All dimensions are nominal											
Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBT16244DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74CBT16244DGVR	TVSOP	DGV	48	2000	330.0	24.4	6.8	10.1	1.6	12.0	24.0	Q1
SN74CBT16244DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1



PACKAGE MATERIALS INFORMATION

11-Mar-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBT16244DGGR	TSSOP	DGG	48	2000	346.0	346.0	41.0
SN74CBT16244DGVR	TVSOP	DGV	48	2000	346.0	346.0	41.0
SN74CBT16244DLR	SSOP	DL	48	1000	346.0	346.0	49.0

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



MSSO001C - JANUARY 1995 - REVISED DECEMBER 2001

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

DL (R-PDSO-G**)



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118



PLASTIC SMALL-OUTLINE

MPDS006C - FEBRUARY 1996 - REVISED AUGUST 2000

DGV (R-PDSO-G**)

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153

14/16/20/56 Pins – MO-194



MCFP010B - JANUARY 1995 - REVISED NOVEMBER 1997

CERAMIC DUAL FLATPACK

WD (R-GDFP-F**)

48 LEADS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only
 - E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA
 - GDFP1-F56 and JEDEC MO-146AB



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